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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Sung-Fei WANG, et al

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Washington, DC 20231

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SUBSTITUTE DECLARATION

Sir:

Kindly substitute the attached Combined Declaration and Power of Attorney with the original ink signature for the document previously filed on March 1, 2002.

Respectfully submitted,


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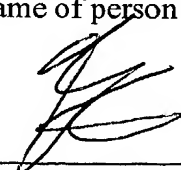
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